



Device Material Content

5555 NE Moore Ct.
Hillsboro OR 97124
(503) 268-8000

Package: 24 QFNS with matte Sn Plating
Total Device Weight 0.042 Grams

MSL: 1
Peak Reflow Temp: 260°C

October, 2009	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	Notes / Assumptions:
Die	5.55%	0.0023			Silicon chip	7440-21-3	Die size: 2.00 x 2.00 mm
Mold	56.46%	0.0237	49.69%	0.0209	Silica (fused)	60676-86-0	Mold Compound Density ranges between 1.9 and 2.1 grams/cc 75 to 95% Fused silica filler (LSC uses 88% in our calculation) 2 to 10% Epoxy resin (LSC uses 5% in our calculation) 2 to 10% Phenol resin (LSC uses 5% in our calculation) 0.5 to 2.5% Metal hydroxide (LSC uses 1.75% in our calculation) 0.1 to 0.5% Carbon Black (LSC uses 0.25% in our calculation)
			2.82%	0.0012	Epoxy Resin	-	
			2.82%	0.0012	Phenol Resin	-	
			0.99%	0.0004	Metal Hydroxide	-	
			0.14%	0.0001	Carbon Black	1333-86-4	
D/A Epoxy	0.97%	0.0004	0.73%	0.0003	Silver (Ag)	7440-22-4	Die attach epoxy Density: 4 grams/cc 70 to 80% Silver (LSC uses 75% in our calculation) 20 to 30% Organic Resins, Hardners and Elastomers (LSC uses 25% in our calculation)
			0.24%	0.0001	Organic esters and resins	-	
Wire	0.67%	0.0003			Gold (Au)	7440-57-5	Assume 1 wire per lead
Plating	2.10%	0.0009			Tin (Sn)	7440-31-5	Tin plating is 400 to 800 microinches (LSC uses 600 microinches in our calculation)
Leadframe	34.25%	0.0144			Copper (Cu)	7440-50-8	

Notes:

The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible.

Constituent substances and proportions in epoxy materials are before curing.

The information provided above is representative of the package as of the date listed, and is subject to change at any time.

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